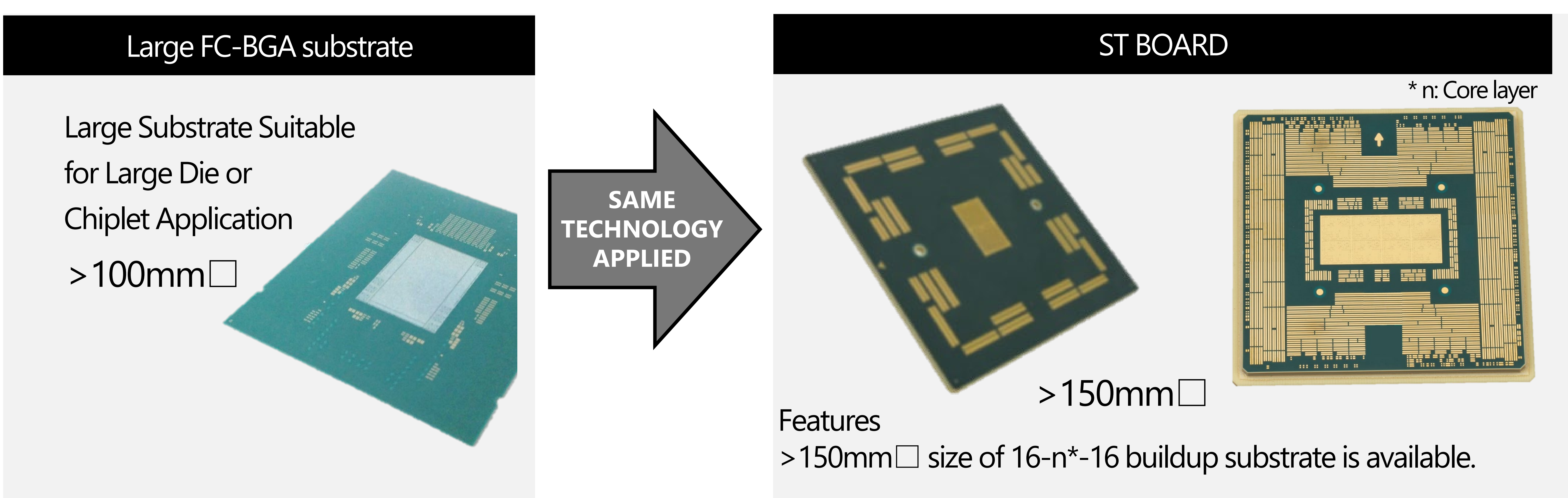
Advanced LSI Test Board

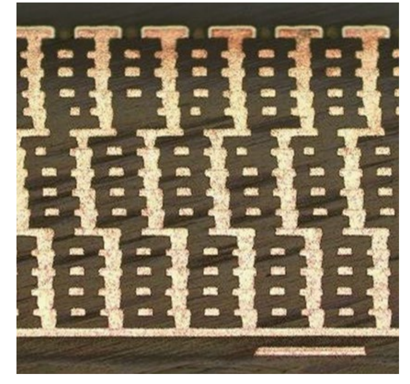
Chip Test Boards with FC-BGA and Ultra-High Multilayer Substrate Technologies

High Performance Space Transformer Substrate

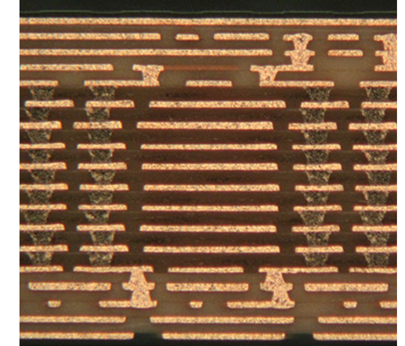


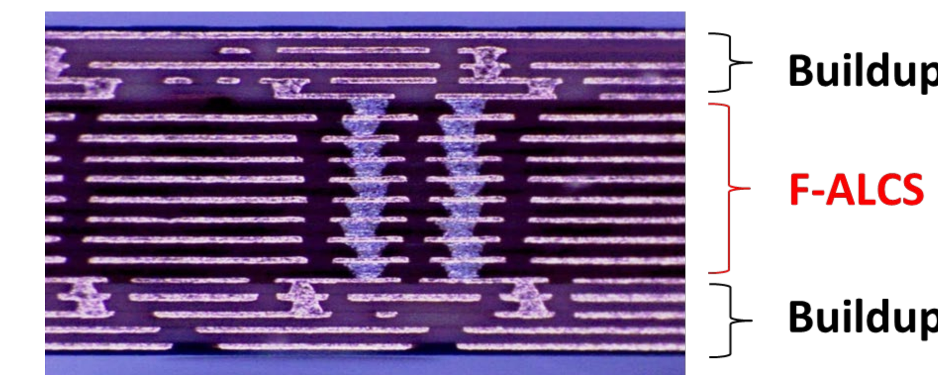
■ Multilayer buildup structure based on FC-BGA SAP*

*Semi Additive Process



16 layers buildup

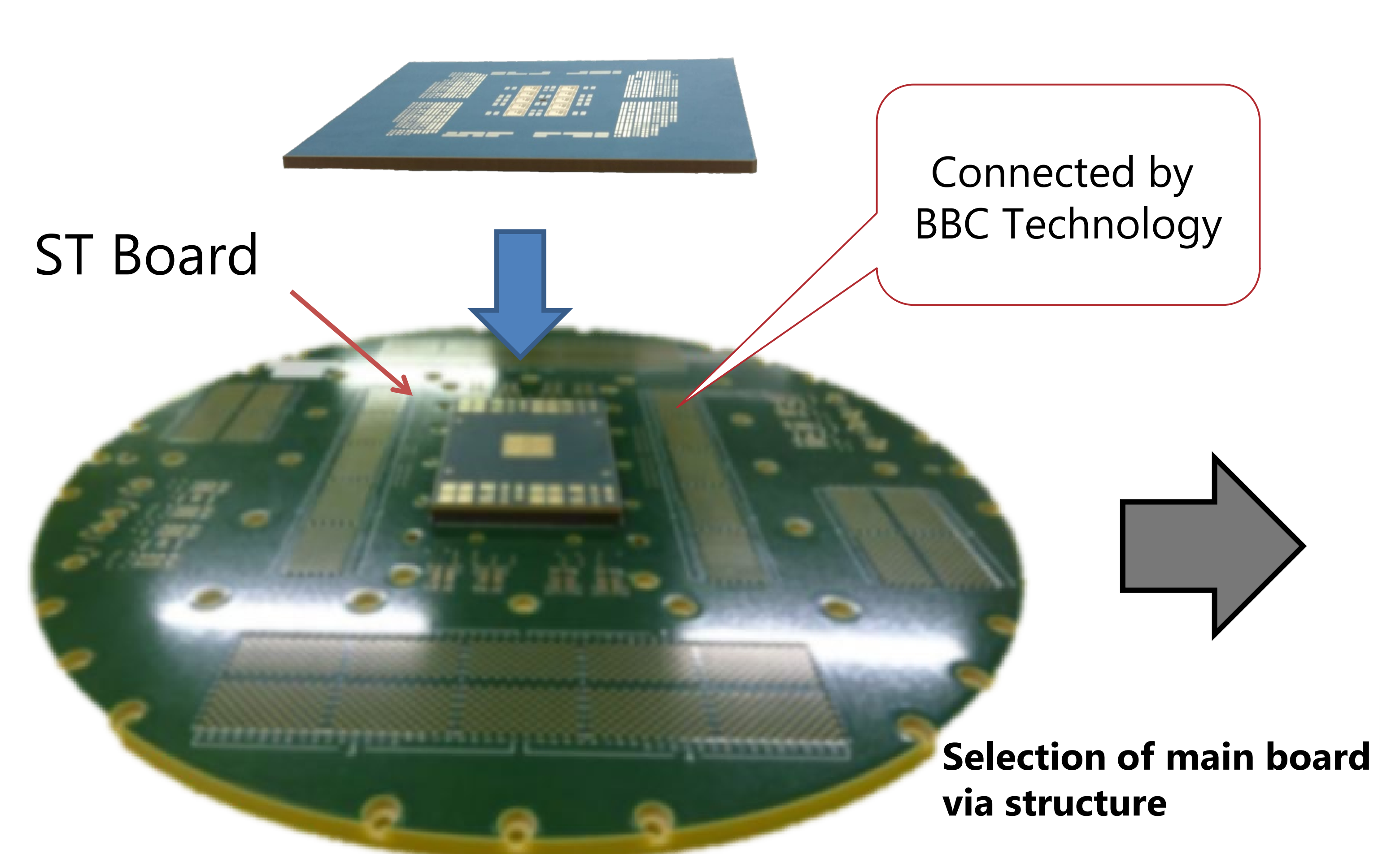




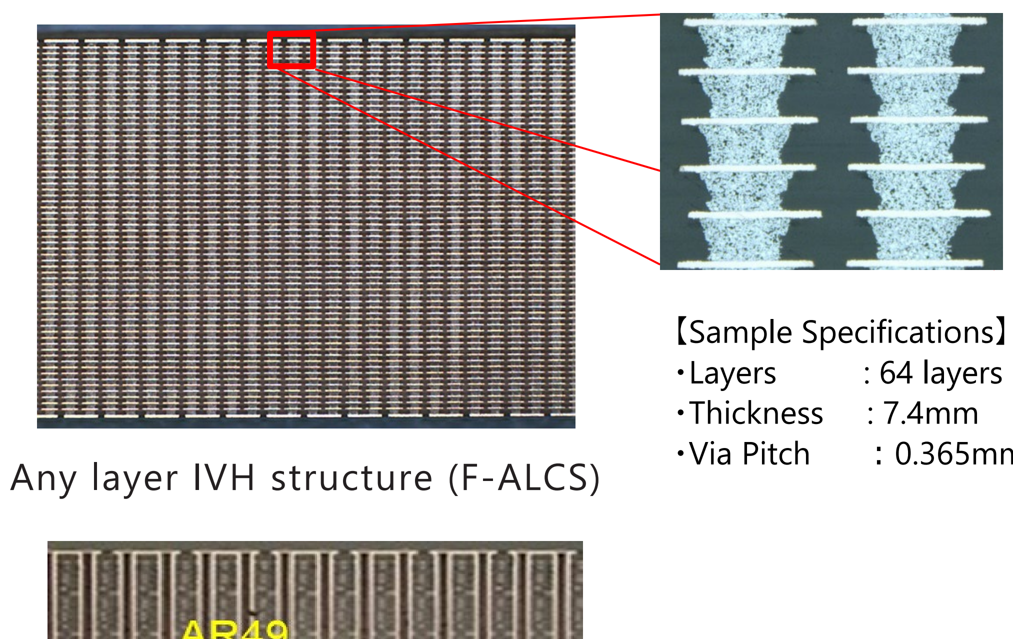
Any layer IVH with our F-ALCS Technology

ST Substrate and Ultra-High Multilayer Substrate Structure

- ■ FC-BGA substrate technology and ultra-high multilayer substrate technology
- ■ Via structures for ultra-high multilayer + ultra-high aspect structures

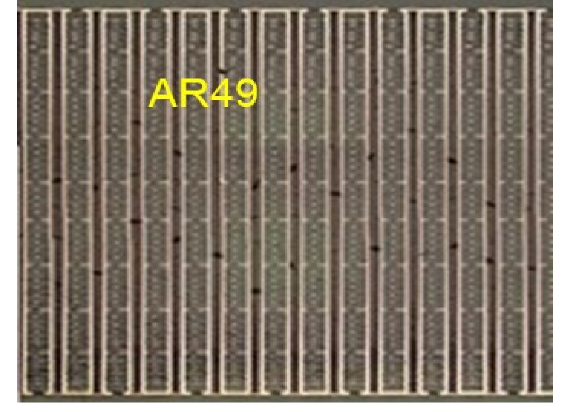


Selection of main board via structure



Any layer IVH structure (F-ALCS)

【Sample Specifications】
- ・Layers : 64 layers
- ・Thickness : 7.4mm
- ・Via Pitch : 0.365mm



High aspect through hole structure

【 Sample Specifications 】
- ・Layers : 106 layers
- ・Thickness : 7.4mm
- ・Via Pitch : 0.4mm